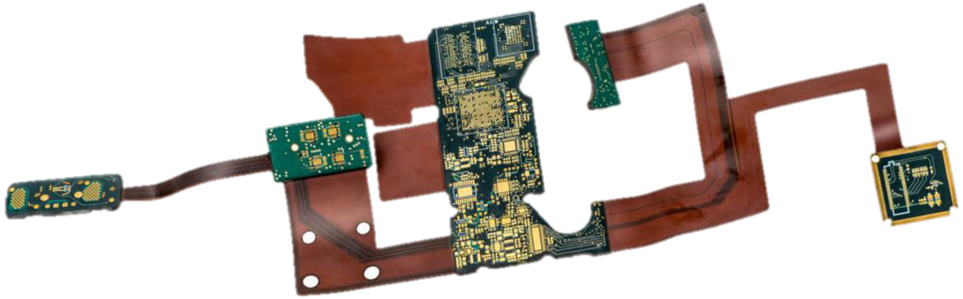
Rigid Flex Capabilities



	Standard	Advanced
Panel Size	18” by 24”	18” by 24”
Layer Count	4 to 20	21 to 30
Pouching/Cutback Cover/Pouching	Standard Practice	Standard Practice
Line Width and Spacing (Inner Layer)	.003” / .003” [76 µm / 76 µm]	.002” / .002” [51 µm / 51 µm]
Line Width and Spacing (Outer Layer)	.004” / .004” [101 µm / 101 µm]	.003” / .003” [76 µm / 76 µm]
Min Via (Drilled)	.0079” [0.200 mm]	.006” [0.152 mm]
Min Via (Laser)	.006” [0.152 mm] *(Blind Via) , > 1:1 Aspect Ratio*	.004” [0.101 mm] *(Blind Via) , > 1:1 Aspect Ratio*
Min Pad Size	Via + 0.01”	Via + 0.008”
Mechanical Drill Aspect Ratio	10:1	Greater than 10:1
Min Copper Weight	9 Micron	9 Micron
Max Copper Weight	2 oz.	3 oz.

Rigid Flex Capabilities Continued

	Standard	Advanced
Min Core Thickness	.002” [51 µm]	.001” [25 µm]
Plating Options	ENIG, ENEPIG, HASL, Electroplated nickel/gold	EPIG, ENIG, ENEPIG, HASL, Electroplated nickel/gold
Min Via Fill Hole Size Drill	.0118” [0.300 mm] *up to .080” [2.03 mm] PCB Thickness*	.0098” [0.249mm] *up to .062” [1.57mm] PCB Thickness*
Min Soldermask Web	.005”	.004”
Impedance Tolerance	±10%	±5%
Copper to Board Edge	±.005” Routed	±.004” Laser
Coverlayers/Bondplies	Dupont LF, FR	Dupont HT
Via Structure	Thru-hole, Buried	Blind